

Microprocessor Supervisory Circuit

ADM1232

FEATURES

Superior Upgrade for MAX1232 and Dallas DS1232 Low Power Consumption (500 µA max) Adjustable Precision Voltage Monitor with +4.5 V and +4.75 V Options

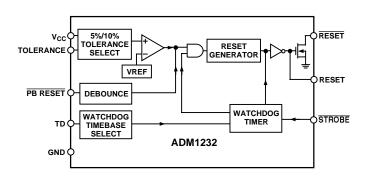
Adjustable STROBE Monitor with 150 ms, 600 ms or 1.2 sec Options

No External Components

APPLICATIONS
Microprocessor Systems
Portable Equipment
Computers
Controllers
Intelligent Instruments

Automotive Systems
Protection Against Damage Caused by μP Failure

FUNCTIONAL BLOCK DIAGRAM



GENERAL DESCRIPTION

The ADM1232 is a superior, pin-compatible upgrade for the MAX1232 and the DS1232LP and DS1232. The Analog Devices ADM1232 is a microprocessor monitoring circuit that can monitor:

- 1. Microprocessor Supply Voltage.
- 2. Whether a Microprocessor has locked-up.
- 3. An External Interrupt.

The ADM1232 is available in four different packages:

- 1. The ADM1232ARM in an 8-lead microSOIC (RM-8).
- 2. The ADM1232AN in an 8-lead PDIP (N-8).
- 3. The ADM1232ARW in a 16-lead wide SOIC (R-16).
- 4. The ADM1232ARN is an 8-lead narrow SOIC (R-8).

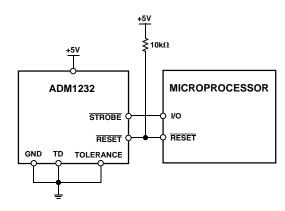


Figure 1. Typical Supply Monitoring Application

$\begin{subarray}{c} \textbf{ADM1232--SPECIFICATIONS} & (\textbf{V}_{\texttt{CC}} = \textbf{Full Operating Range}, \textbf{T}_{\texttt{A}} = \textbf{T}_{\texttt{MIN}} \ \text{to T}_{\texttt{MAX}} \ \text{unless otherwise noted}) \\ \end{subarray}$

Parameter	Min	Тур	Max	Units	Test Conditions/Comments
TEMPERATURE	-40		+85	°C	$T_A = T_{MIN}$ to T_{MAX}
POWER SUPPLY					
Voltage	4.5	5.0	5.5	V	
Current		20	50	μA	V_{IL} , V_{IH} = CMOS Levels
		200	500	μA	V_{IL} , V_{IH} = TTL Levels
STROBE AND PB RESET INPUTS					
Input High Level	2.0		$V_{CC} + 0.3$	V	
Input Low Level	-0.3		+0.8	V	
INPUT LEAKAGE CURRENT					
(STROBE, TOLERANCE)	-1.0		+1.0	μA	
TD		1.6		μA	
OUTPUT CURRENT					
RESET	2.0	10		mA	When RESET Is at 2.4 V
RESET, RESET	-1.0	-12		mA	When RESET Is at 0.4 V
RESET		50		μΑ	When RESET Is at 0.4 V
V _{CC} TRIP POINT					
5%	4.5	4.62	4.74	V	TOLERANCE = GND
10%	4.25	4.37	4.49	V	TOLERANCE = V_{CC}
CAPACITANCE					
Input (STROBE, TOLERANCE)			5	рF	$T_A = +25^{\circ}C$
Output (RESET, RESET)			7	pF	$T_A^{\text{T}} = +25^{\circ}\text{C}$
PB RESET					
Time	20			ms	PB RESET Must Be Held Low for a Minimum of
Delay	1	4	20	ms	20 ms to Guarantee a Reset
RESET ACTIVE TIME	250	610	1000	ms	
STROBE					
Pulse Width	70			ns	
Timeout Period	62.5	150	250	ms	TD = 0 V
	250	600	1000	ms	TD = Floating
	500		2000	ms	$TD = V_{CC}$
$\overline{V_{CC}}$					
Fall Time	10			μs	Guaranteed by Design
Rise Time	0			μs	Guaranteed by Design
V _{CC} FAIL DETECT TO RESET OUTPUT DELAY					
RESET AND RESET Are Logically Correct			50	μs	After V _{CC} Falls Below the Set Tolerance Voltage (Figure 5)
TELEST THE TELEST THE LOgically Contect	250	610	1000	ms	After V_{CC} Pairs below the Set Tolerance Voltage (Figure 3)
	250	010	1000	1112	There ver reses move the set rolerance voltage

Specifications subject to change without notice.

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ADM1232

ABSOLUTE MAXIMUM RATINGS*

 $(T_{A} = +25^{\circ}\text{C unless otherwise noted})$ $V_{CC} \qquad \qquad +5.5 \text{ V}$ $Logic Inputs \qquad -0.3 \text{ V to V}_{CC} + 0.3 \text{ V}$ $Storage Temperature Range \qquad -65^{\circ}\text{C to } +150^{\circ}\text{C}$ $Lead Temperature (Soldering, 10 sec) \qquad +300^{\circ}\text{C}$

Vapor Phase (60 sec) ... +215°C
Infrared (15 sec) ... +220°C
N-8

 $\begin{array}{llll} Power \ Dissipation & ... & 1000 \ mW \\ Derate \ by \ 13.5 \ mW/^{\circ}C \ above \ 25^{\circ}C \\ \theta_{JA} \ Thermal \ Impedance & ... & 100^{\circ}C/W \end{array}$

R-16
Power Dissipation
Derate by 12 mW/°C above 25°C
θ_{JA} Thermal Impedance (Still Air)
RM-8
Power Dissipation 900 mW
Derate by 12 mW/°C above 25°C
θ _{JA} Thermal Impedance (Still Air) 206°C/W
R-8
Power Dissipation900 µW
Derate by 12 mW/°C above 25°C
θ _{IA} Thermal Impedance (Still Air) 153°C/W

^{*}Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum ratings for extended periods of time may affect device reliability.

ORDERING GUIDE

Model	Temperature Range	Package Options*
ADM1232ARM	-40°C to +85°C	RM-8
ADM1232AN	-40°C to +85°C	N-8
ADM1232ARW	-40°C to +85°C	R-16
ADM1232ARN	-40°C to +85°C	R-8

^{*}N= Plastic DIP; R = Small Outline; RM = microSOIC.

CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the ADM1232 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



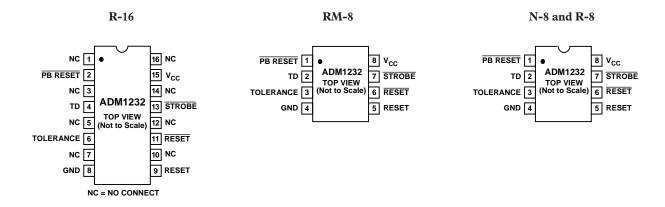
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ADM1232

PIN FUNCTION DESCRIPTIONS

Mnemonic	Function
PB RESET	Push Button Reset Input. This debounced input will ignore pulses of less than 1 ms and is guaranteed to respond to pulses greater than 20 ms.
TD	Time Delay Set allows the user to select the maximum amount of time the ADM1232 will allow the STROBE input to remain inactive (i.e., STROBE is not receiving any high-to-low transitions), without forcing the ADM1232 to generate a RESET pulse. (See STROBE specifications, Figure 4 and the note on STROBE timeout selection.)
TOLERANCE	Tolerance Input. This input will determine how much the supply voltage will be allowed to decrease (as a percentage tolerance) before a RESET is asserted. Connect to V_{CC} for 10% and GND for 5%.
GND	0 V ground reference for all signals.
RESET	Active high logic output. Will be asserted when: 1. V _{CC} decreases below the amount specified by the TOLERANCE input or, 2. PB RESET is forced low or, 3. If there are no high-to-low transitions within the limits set by TD at STROBE or, 4. During power-up.
RESET	Inverse of RESET, with an open drain output.
STROBE	The STROBE input is used to monitor the activity of a microprocessor. If there are no high-to-low transitions within the time specified by TD, a reset will be asserted.
V_{CC}	Power supply input +5 V.

PIN CONFIGURATIONS



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ADM1232

CIRCUIT INFORMATION PB RESET

The PB RESET input makes it possible to manually reset a system using either a standard push-button switch or a logic low input. An internal debounce circuit provides glitch immunity when used with a switch, reducing the effects of glitches on the line. The debounce circuit is guaranteed to cause the ADM1232 to assert a reset if PB RESET is brought low for more than 20 ms and is guaranteed to ignore low inputs of less than 1 ms.

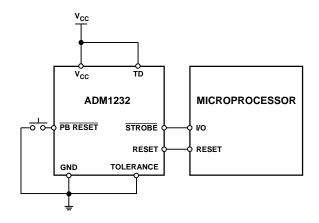


Figure 2. Typical Push Button Reset Application

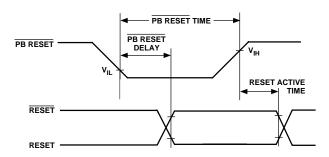


Figure 3. PB RESET

STROBE Timeout Selection

TD or time delay set is used to set the Strobe Timeout Period. The Strobe Timeout Period is defined as being the maximum time between high-to-low transitions (Figure 4) that \overline{STROBE} will accept before a reset will be asserted. The Strobe timeout settings are listed in Table I.

Table I.

Condition	Min	Тур	Max	Units
TD = 0 V	62.5	150	250	ms
TD = Floating	250	600	1000	ms
$TD = V_{CC}$	500	1200	2000	ms

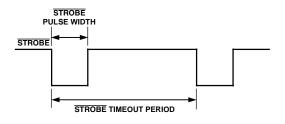


Figure 4. STROBE Parameters

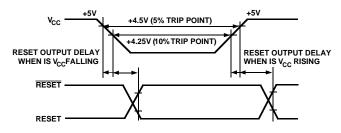


Figure 5. Reset Output Delay

TOLERANCE

The TOLERANCE input is used to determine the level $V_{\rm CC}$ can vary below 5 V without the ADM1232 asserting a reset. Connecting TOLERANCE to ground will select a –5% tolerance level and will cause the ADM1232 to generate a reset if $V_{\rm CC}$ falls below 4.75 V (typical). If TOLERANCE is connected to $V_{\rm CC}$ a –10% tolerance level is selected and will cause the ADM1232 to generate a reset if $V_{\rm CC}$ falls below 4.5 V (typical). Check the parameters for the $V_{\rm CC}$ trip point in the ADM1232 Specifications for more information.

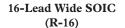
RESET AND RESET OUTPUTS

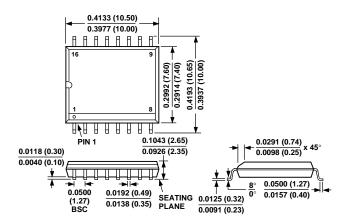
While RESET is capable of sourcing and sinking current, RESET is an open drain MOSFET which sinks current only. Therefore, it is necessary to pull this output high.

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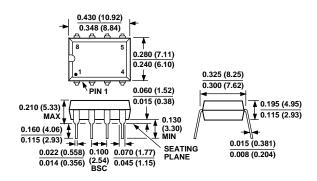
OUTLINE DIMENSIONS

Dimensions shown in inches and (mm).

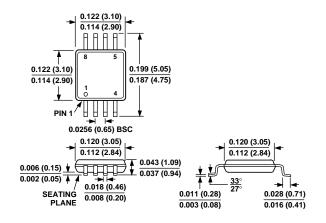




8-Lead PDIP (N-8)



8-Lead microSOIC (RM-8)



8-Lead Narrow SOIC (R-8)

